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New Developments in 3D Analytical Electron Tomography

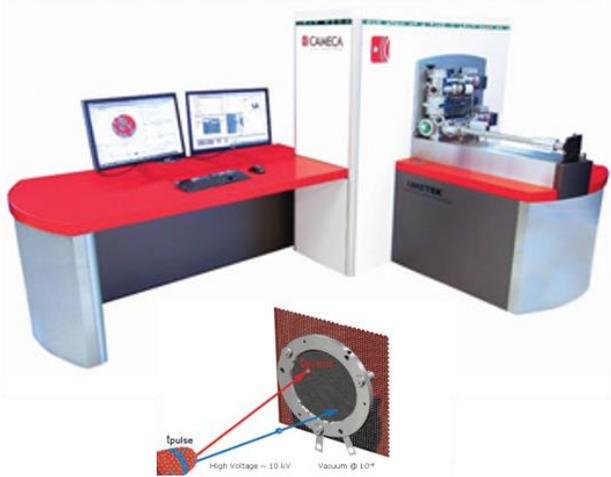
Zineb Saghi

email: zineb.saghi@cea.fr

With the contribution of: Guillaume Biagi, Martin Jacob, Audrey Jannaud, Gabriele Navarro, Mei-Lin Grouzelle, Frédéric Lorut, Jean-Luc Starck and Philippe Ciuciu.

3D CHARACTERIZATION TECHNIQUES AT THE NANOSCALE

Atom probe tomography



Field ion microscope combined with a mass spectrometer

Electron tomography

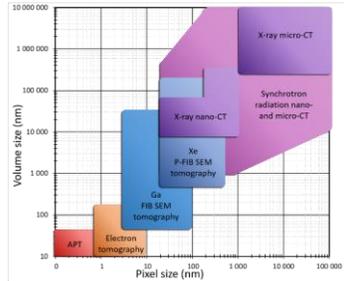
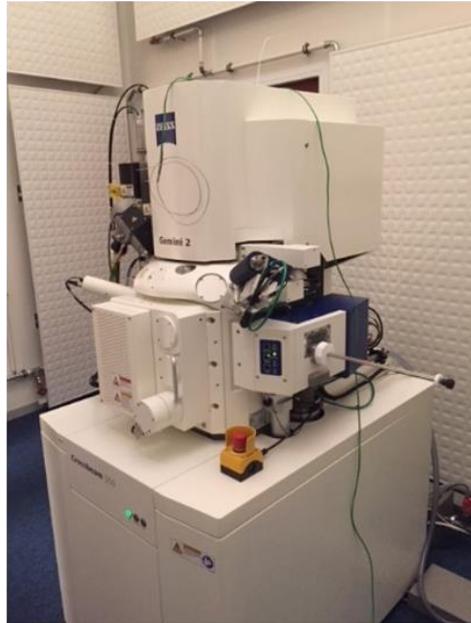


Transmission electron microscope (TEM)

Slice-and-view tomography

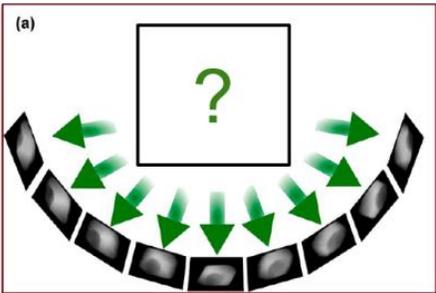


Focussed ion beam combined with a scanning electron microscope (FIB-SEM)

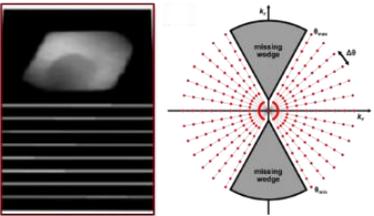


BASICS OF ELECTRON TOMOGRAPHY

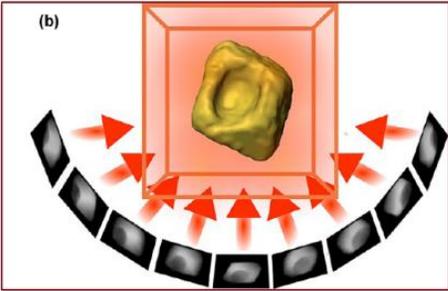
- In electron tomography, 3D volumes are reconstructed from a set of 2D projections acquired inside a transmission electron microscope.
- *Very promising* technique for the 3D analysis of semiconductor materials and devices, catalytic systems, polymers, biological structures, etc.
- Well-established for 3D *morphological* analysis.



1. Acquisition



2. Alignment

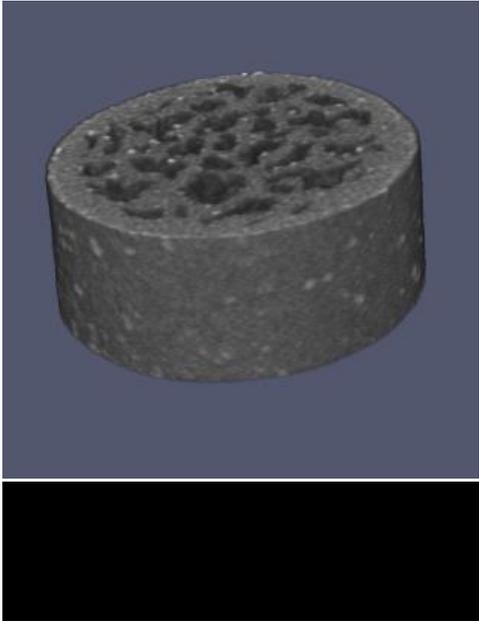


3. Reconstruction

HAADF-STEM tilt series
-90°:1°:+90°



3D HAADF-STEM
reconstruction

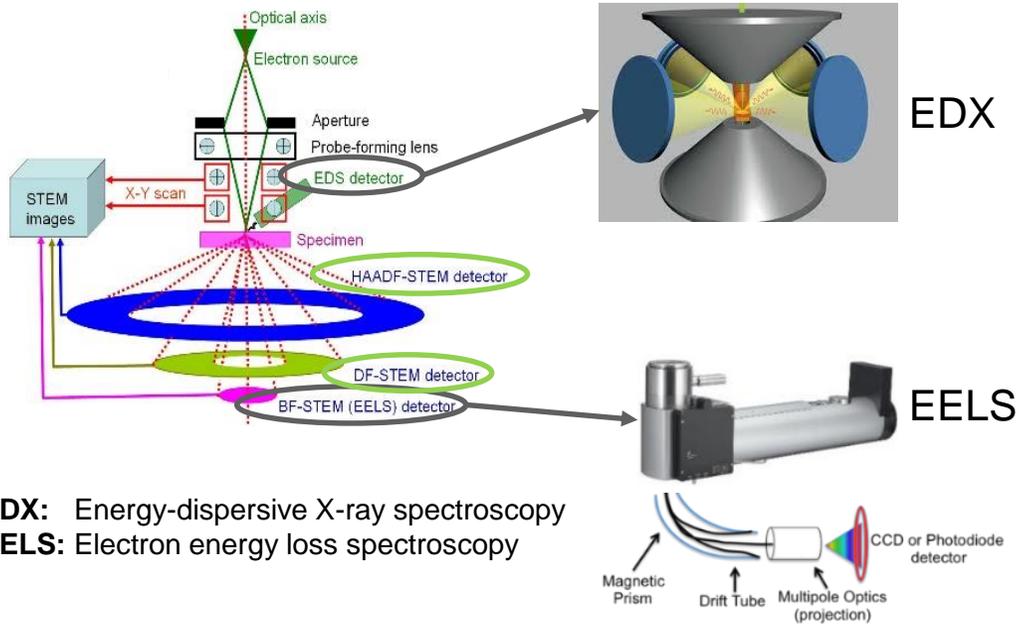


HAADF-STEM tomography of an Er-doped porous silicon structure (G. Mula et al. Scientific Reports 2017, 7:5957)

ANALYTICAL ELECTRON TOMOGRAPHY USING MODERN TEMs

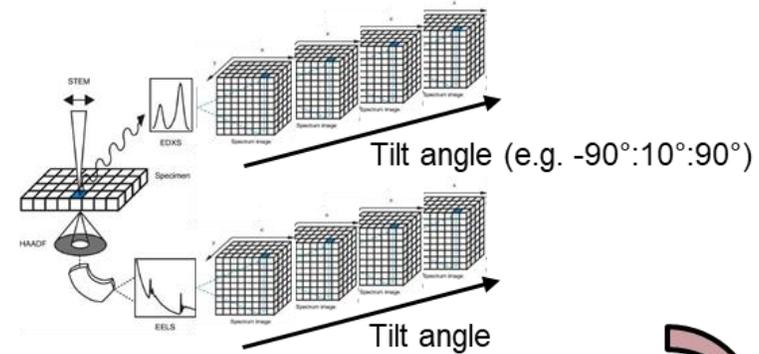
Advances in instrumentation:

- High-brightness sources (Cold and Schottky-type field emission guns)
- EDX detectors with large solid angles ($>0.7\text{sr}$) and high detection efficiency (Silicon drift detectors).
- EELS spectrometers with high-speed (>1000 spectra/s) and high-performance electronics (direct detection technology).



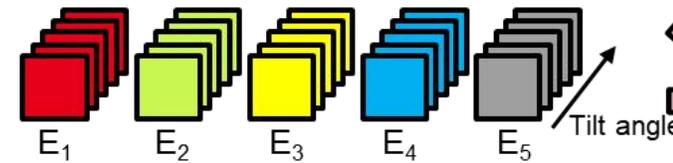
EDX: Energy-dispersive X-ray spectroscopy
EELS: Electron energy loss spectroscopy

Analytical electron tomography using EELS and/or EDS modes:



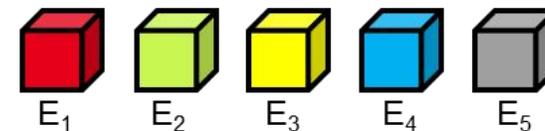
(1) stack of hyperspectral datacubes

Hyperspectral analysis



(2) stacks of elemental maps or chemical phases

Reconstruction

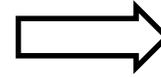


(3) 3D reconstruction for each stack

CHALLENGES RELATED TO ANALYTICAL ELECTRON TOMOGRAPHY

Long acquisition times
High electron doses

(Manual acquisition)



Limited number of projections
Low SNR spectra

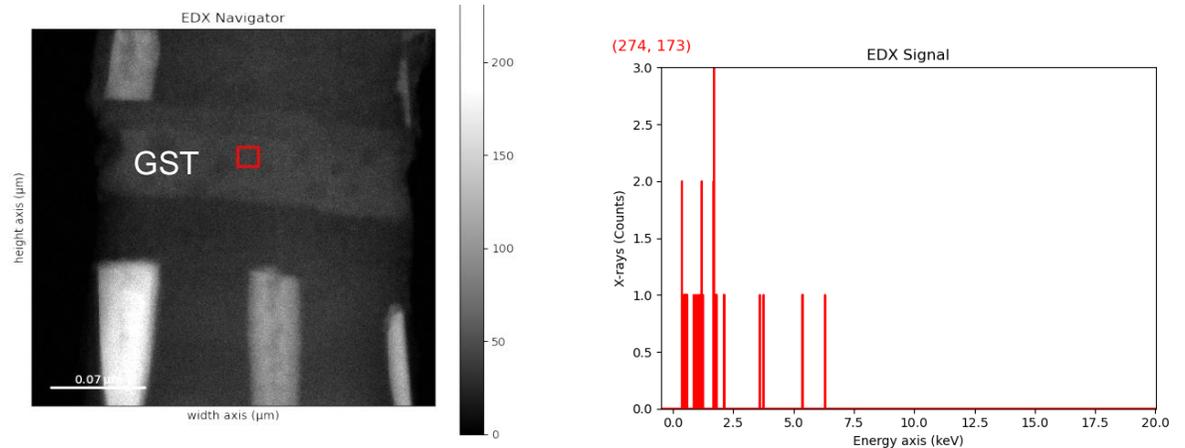
Typical acquisition parameters:

HAADF-STEM tomography:

Probe current: 100pA
Tilt angles: -90°:1°:+90°
Frame size: 2048x2048 pixels
Frame time: 20sec.

STEM-EDX tomography:

Probe current: 200pA-1nA
Tilt angles: -90°:10°:+90°
Frame size: 300x300 pixels.
Acquisition time: 15min.



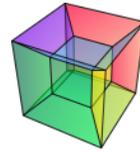
STEM-EDX hyperspectral image.

Acquisition

Data processing

Commercial software **not optimized** for:
Tomographic spectral analysis
3D reconstruction with undersampled data

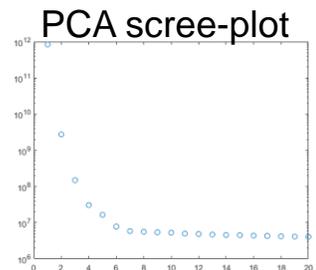
- Fast and automated hyperspectral analysis of tomographic datasets (EELS/EDX)
- Overview of advanced reconstruction algorithms
- Applications of analytical ET:
 - As-doped silicon structure.
 - Ge-Sb-Te (GST)-based phase-change materials.
- Future prospects
 - Hybrid/correlative studies
 - Deep learning for 3D reconstruction under low-dose, limited-angle and sparse-view conditions



HyperSpy
multi-dimensional data analysis

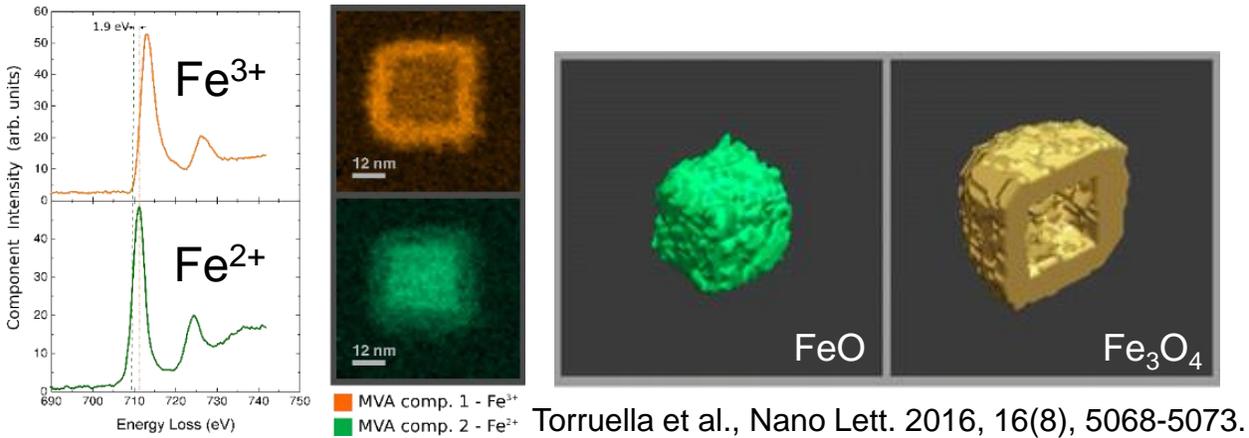
- Tools to import and batch process the full tomographic stack of EELS and/or EDX datacubes
- Denoising by principal component analysis (PCA)
- Elemental mapping :
 - Conventional approach (background subtraction and peak integration)
 - Curve fitting approach (useful for peak separation, no need for a precise spectrum calibration)
- Chemical phase mapping (spectral unmixing approach):
 - Independent component analysis (ICA)
 - Non-negative matrix factorization (NMF)
 - Vertex component analysis (VCA)

Number of components estimation :
Prior knowledge on the observed sample.
PCA scree-plot.

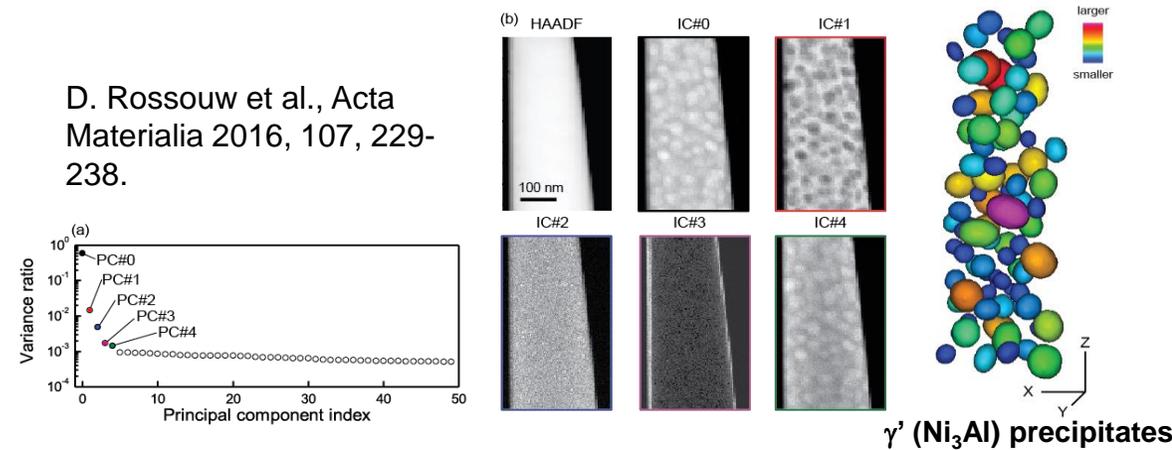


APPLICATIONS OF MULTIVARIATE STATISTICAL ANALYSIS METHODS

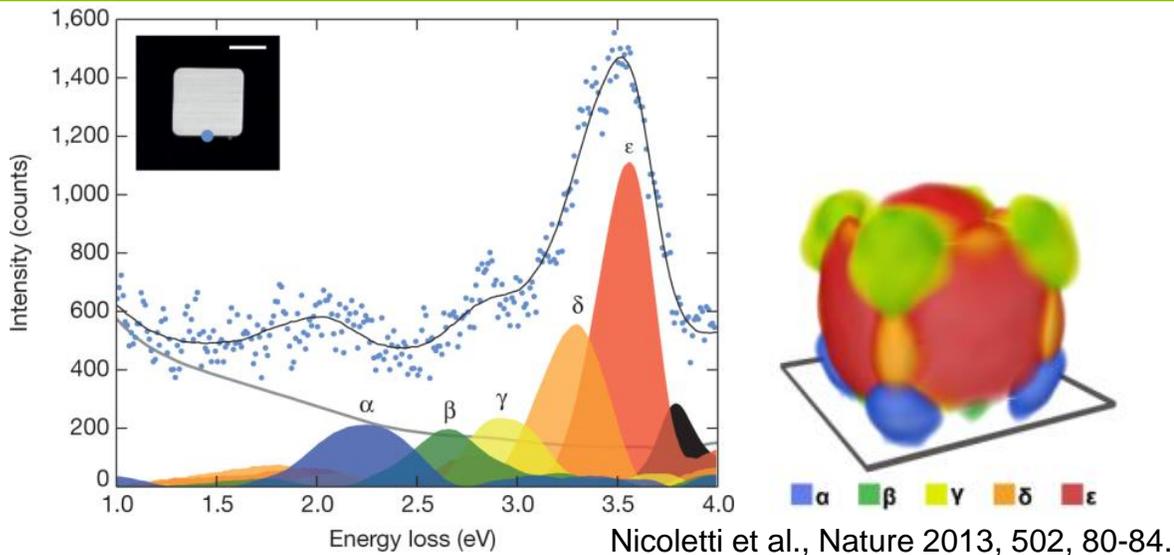
3D visualization of iron oxidation state by STEM-EELS tomography



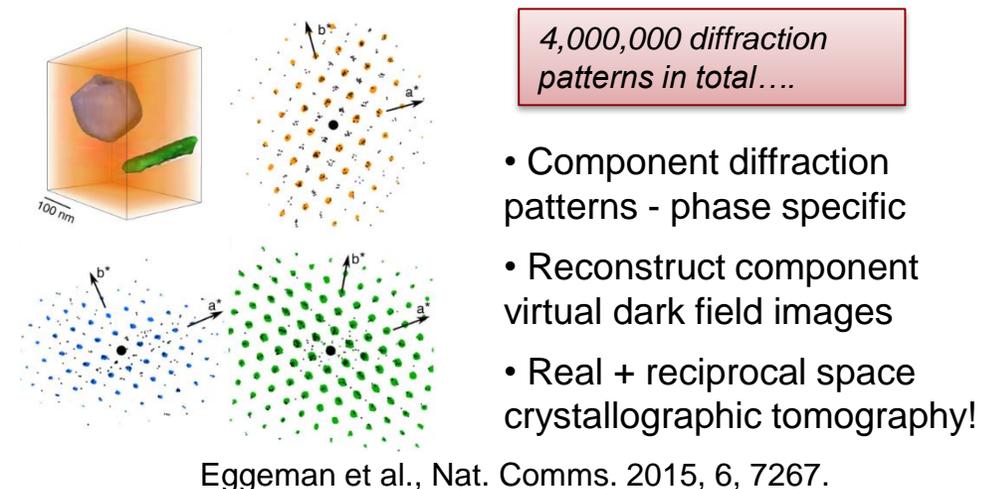
EDX-STEM tomography of nickel-based superalloy



Ag nanocube localised surface plasmon resonances by STEM-EELS tomography

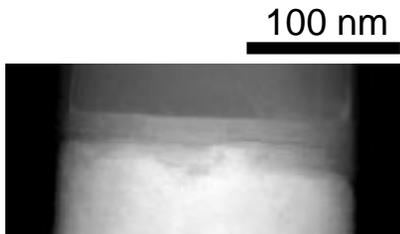


Scanning precession electron tomography of Ni-based superalloy



EDX-STEM TOMOGRAPHY OF A HIGH ELECTRON MOBILITY TRANSISTOR USING NON-NEGATIVE MATRIX FACTORIZATION (NMF)

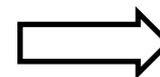
Study of Ti- and Al-Rich Contact Metallization for AlGaIn/GaN high electron mobility transistors



HAADF-STEM

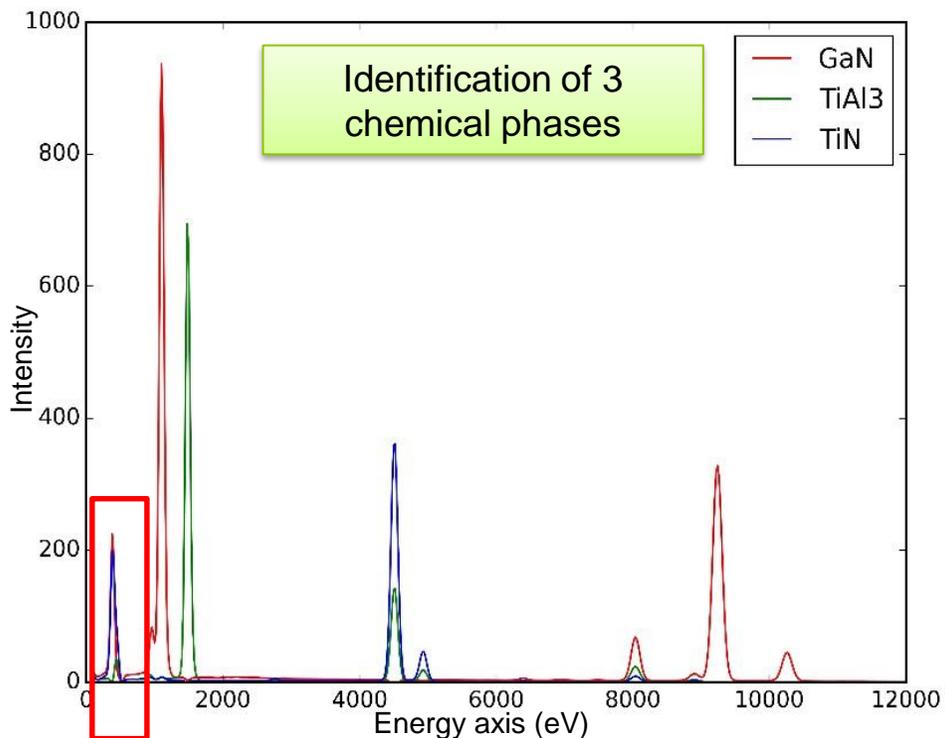
37 EDX-STEM projections
103x200 pixels
5min/map

STEM-EDX tomography

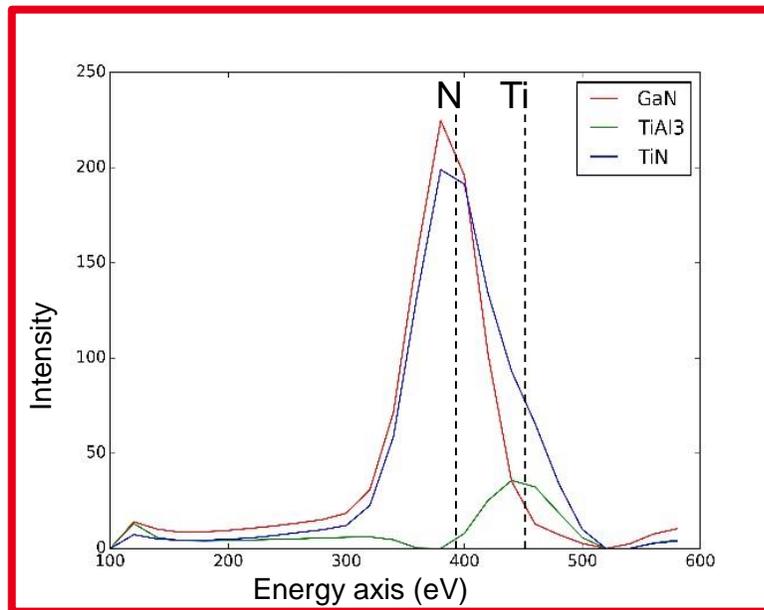


NMF + alignment and reconstruction of the different chemical phase volumes

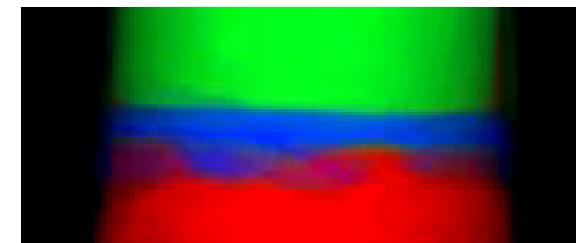
Data processing



Spectral unmixing of the tomographic STEM-EDX dataset



Aligned tilt series



GaN TiAl₃ TiN



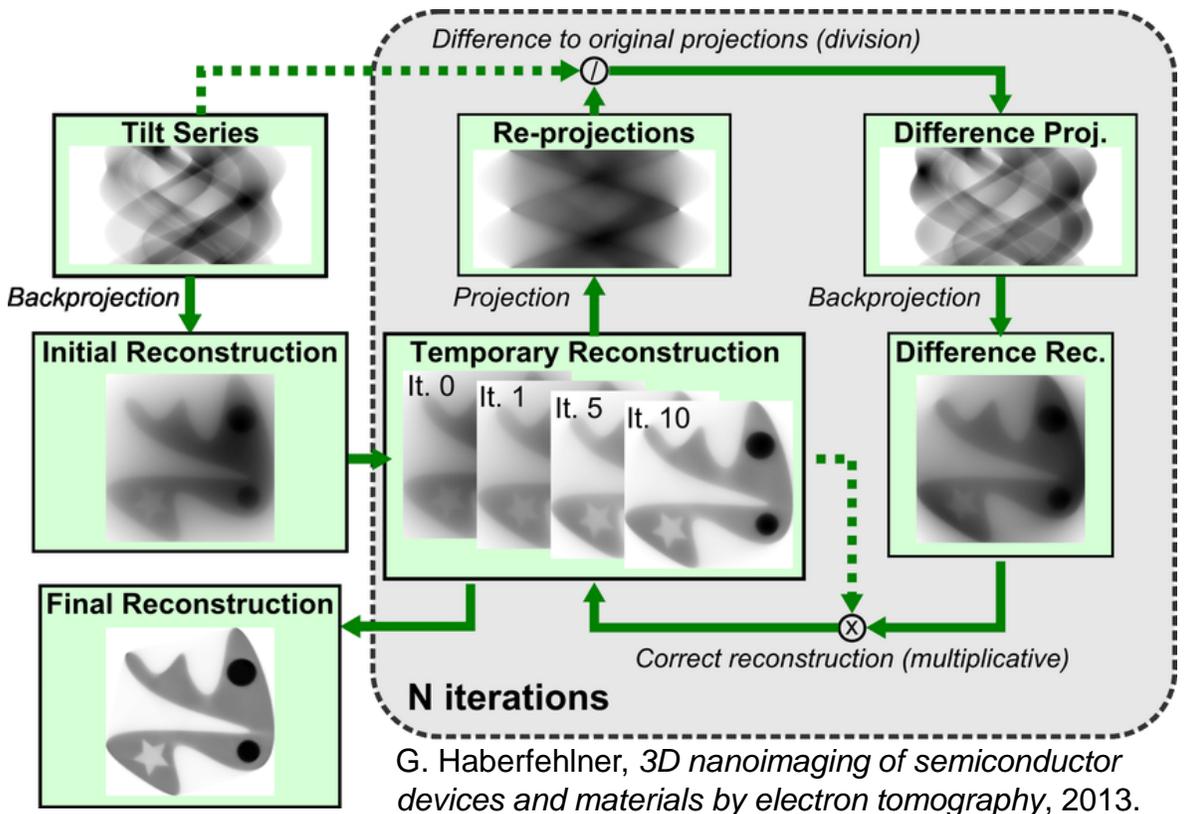
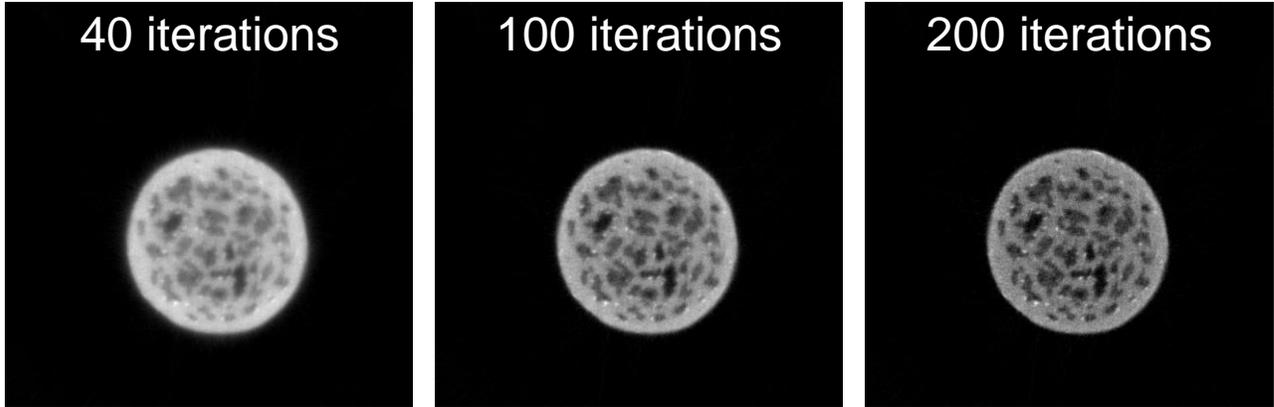
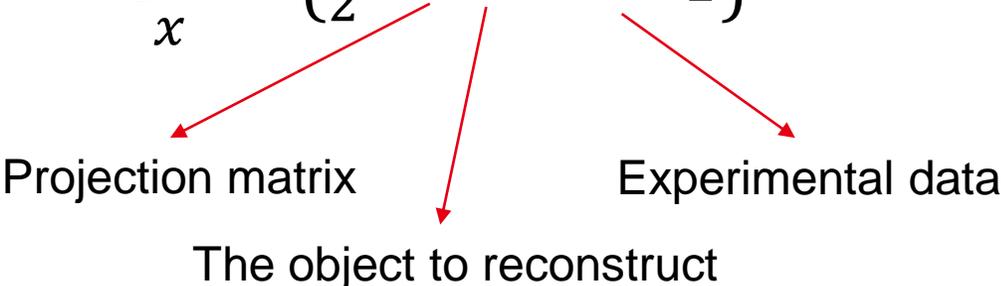
Slices through the 3D reconstruction

- Fast and automated hyperspectral analysis of tomographic datasets (EELS/EDX)
- **Overview of advanced reconstruction algorithms**
- Applications:
 - As-doped silicon structure.
 - Ge-Sb-Te (GST)-based phase-change materials.
- Future prospects
 - Hybrid/correlative studies
 - Deep learning for 3D reconstruction under low-dose, limited-angle and sparse-view conditions

CONVENTIONAL ALGORITHM: SIMULTANEOUS ITERATIVE RECONSTRUCTION TECHNIQUE (SIRT)

SIRT solves the following least squares problem:

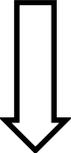
$$\operatorname{argmin}_x \left\{ \frac{1}{2} \|Px - y\|_2^2 \right\}$$



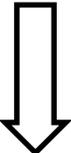
G. Haberfehlner, 3D nanoimaging of semiconductor devices and materials by electron tomography, 2013.

SIMULTANEOUS ITERATIVE RECONSTRUCTION TECHNIQUE (SIRT)

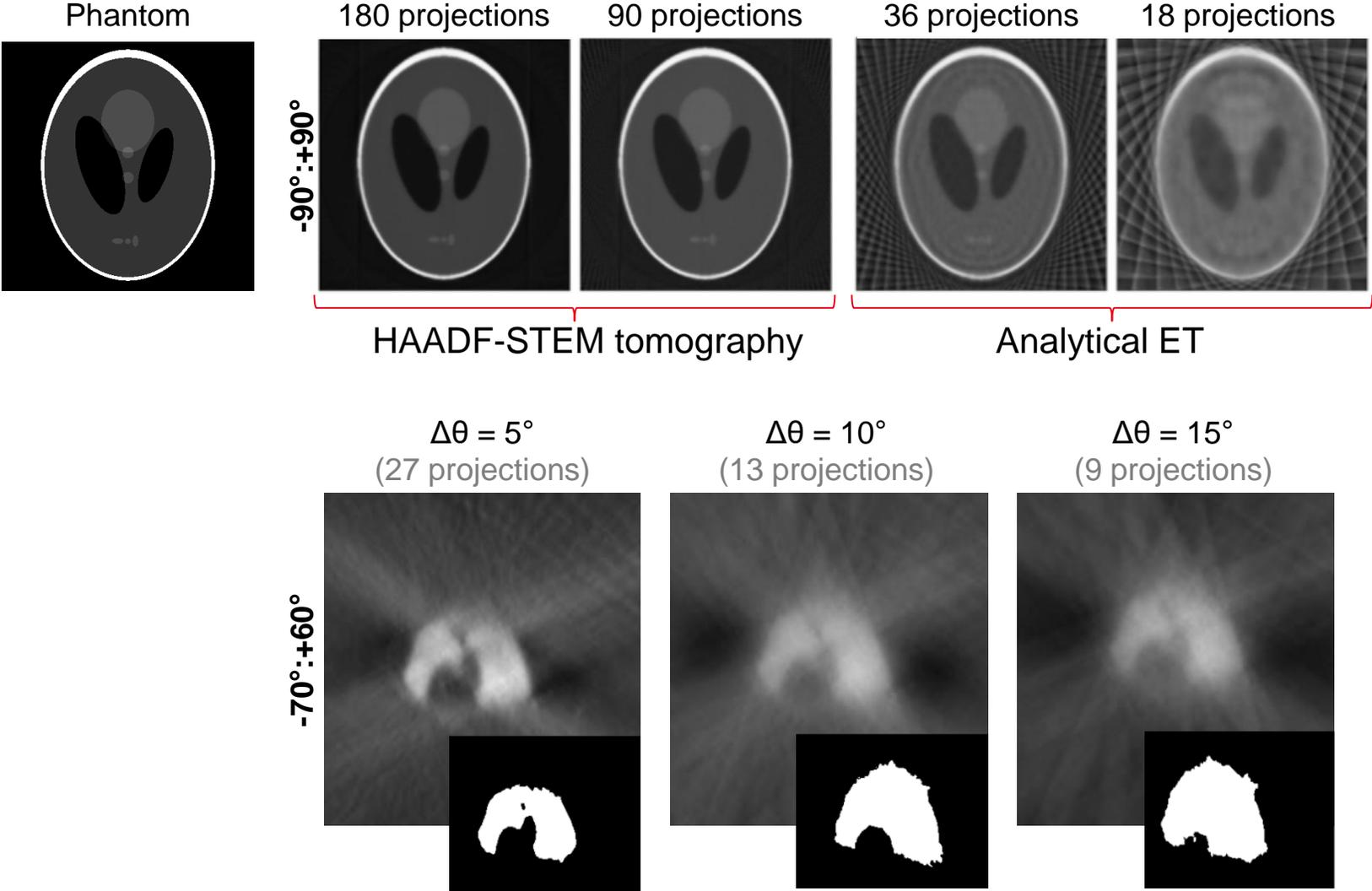
Very limited number of projections



Poor-quality reconstructions



Unreliable segmentation



Z. Saghi et al., Nano Letters 2011, 11(11), 4666.
R. Leary et al., Ultramicroscopy 2013, 131, 70.

Add prior knowledge

Discrete ART (DART)

Compressed sensing (CS)

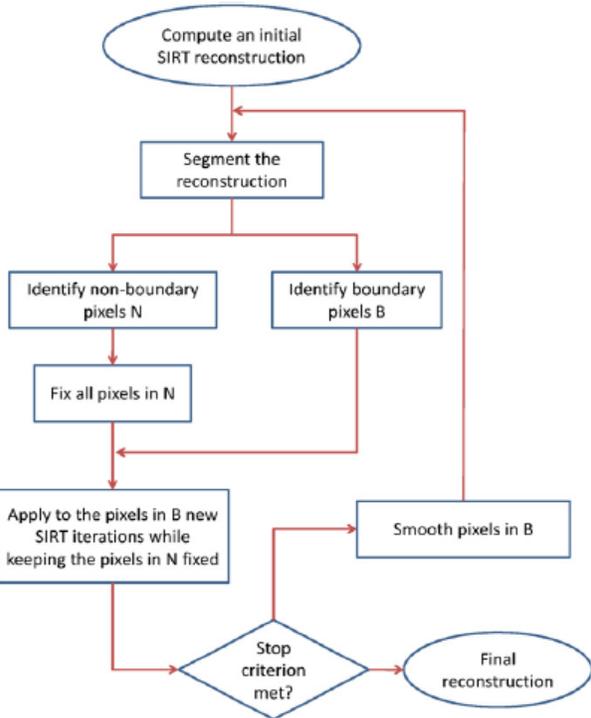
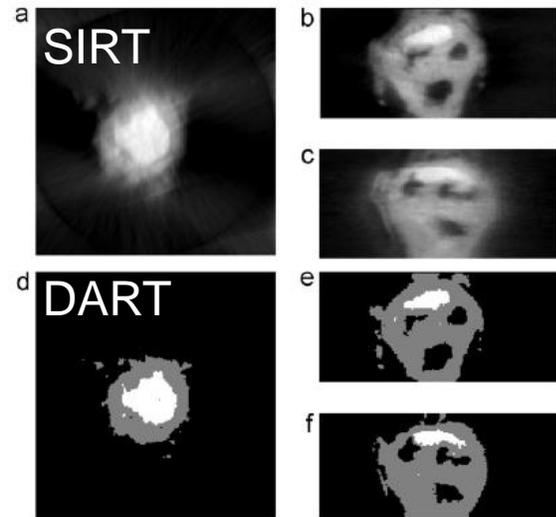


Fig. 2. Flow chart of the DART algorithm.



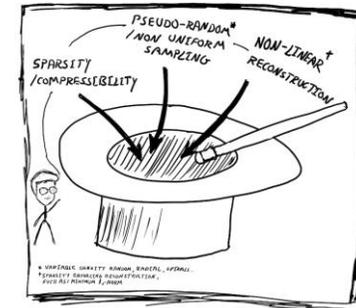
Prior knowledge: number of grey levels, and their intensities.

S. Bals et al. Nano Lett. 2007, 12, 3669
 K.J. Batenburg et al. Ultramicrosc. 2009, 109, 730

$$\operatorname{argmin}_x \left\{ \frac{1}{2} \|Px - y\|_2^2 + \lambda \mathcal{R}(x) \right\}$$

$\mathcal{R}(x) = \|Lx\|_0$ promotes sparsity of x in the transform domain L (few non-zero elements in Lx).

$$\operatorname{argmin}_x \left\{ \frac{1}{2} \|Px - y\|_2^2 + \lambda \|Lx\|_0 \right\}$$



$$\operatorname{argmin}_x \left\{ \frac{1}{2} \|Px - y\|_2^2 + \lambda \|Lx\|_1 \right\}$$

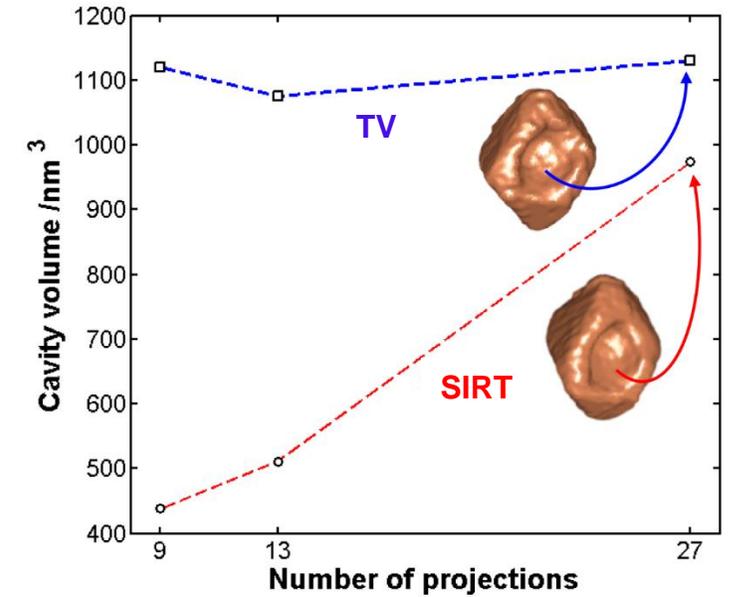
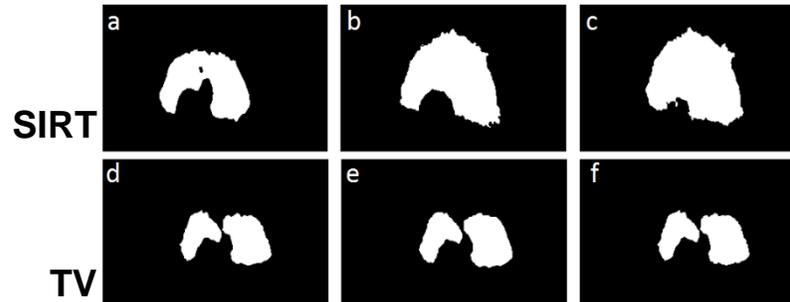
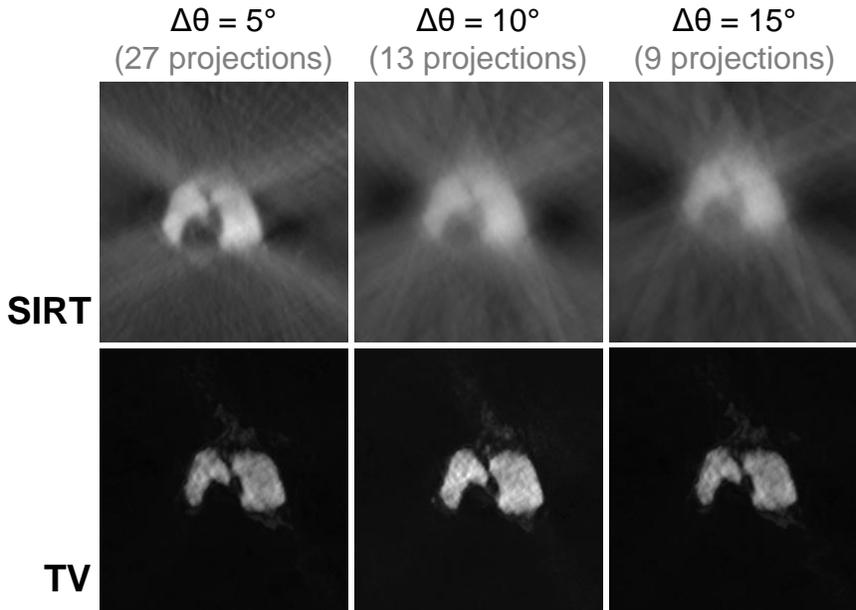
SPARSITY IN THE GRADIENT DOMAIN

Total variation minimization (TV):

TV promotes sparsity in the gradient domain and is very well suited for objects with *piecewise constant regions and sharp edges*

$$\hat{f} = \underset{f}{\operatorname{argmin}} \lambda \|f\|_{TV} + \|\mathbb{R}f - p\|_2^2$$

with: $\|f\|_{TV} = \int |\nabla f(x)| dx$



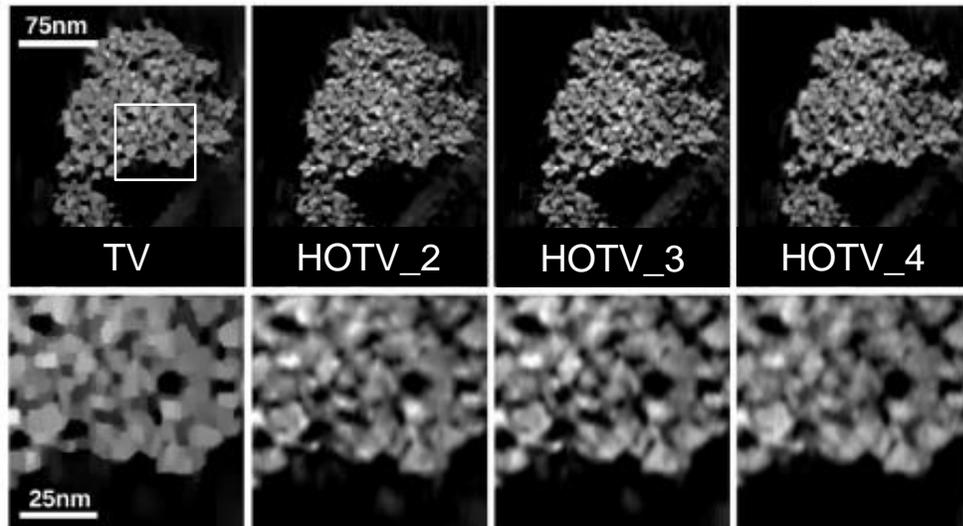
Z. Saghi et al., Nano Letters 2011, 11(11), 4666.
R. Leary et al., Ultramicroscopy 2013, 131, 70.

Limitations of TV:

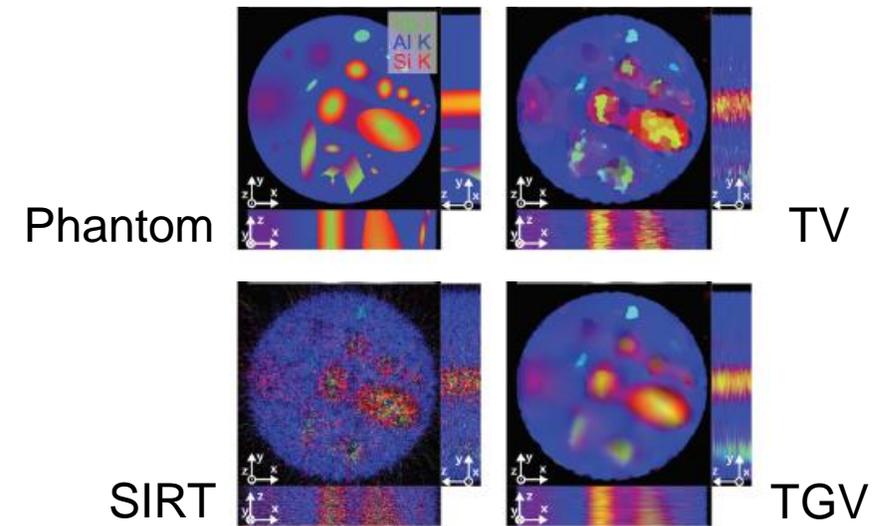
- **Staircase artefacts** when the object is not truly piecewise constant.
- **Complex structures** require more projections than reported for simple objects (Y. Jiang et al. Ultramicrosc. 2017, 186)
- The quality of the reconstructions degrade rapidly in the presence of **Poisson noise**.

Higher order TV (Incorporation of higher order derivatives):

- **HOTV** (ref: R. Archibald et al. J. Sci. Comput. 2015, 67)
- **TGV** (total generalized variation, see e.g.: M. Benning et al. J. Sci. Comput. 2013, 54:269)
- Promote **piecewise smooth regions** while preserving sharp edges.



T. Sanders et al., Ultramicrosc. 2017, 174, 97.

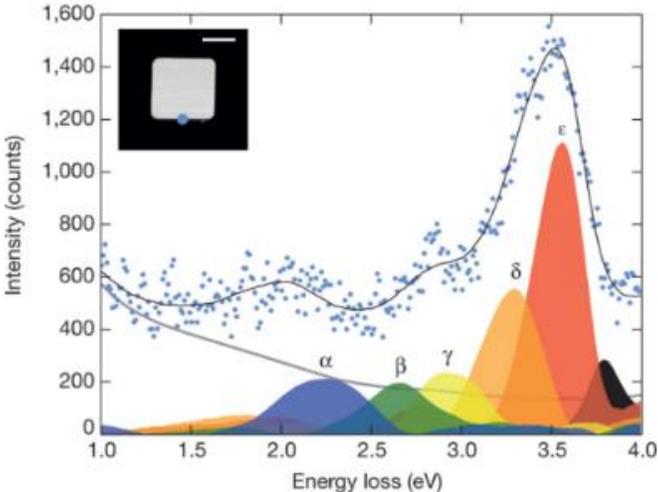
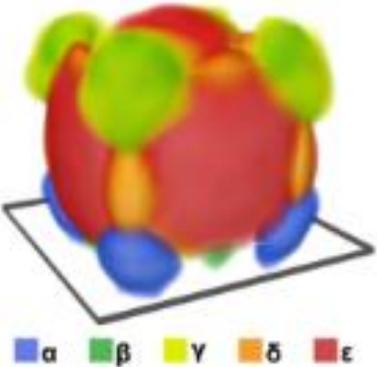


R. Huber et al., Nanoscale 2019, 11, 5617.

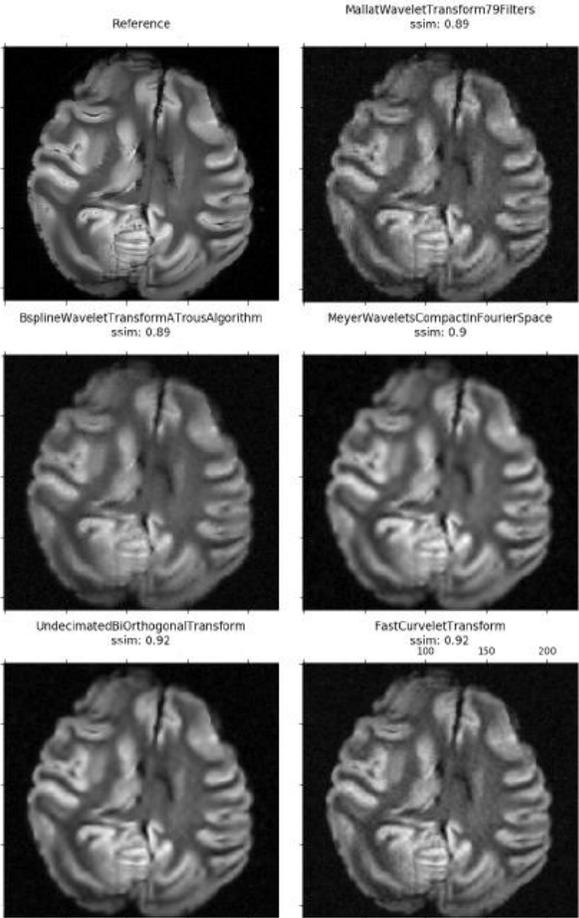
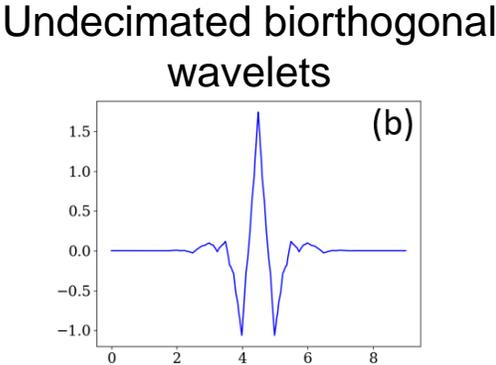
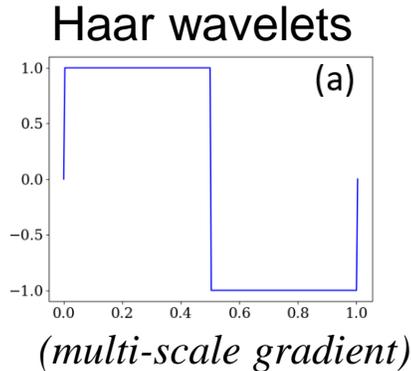
Sparsity in the wavelet domain:

- Multiscale approach used in microscopy mainly for denoising purposes.
- Widely used in MRI and recently applied to CT and ET.
- Applied to a wider range of objects, compared to gradient sparsity.
- Knowledge about the sample => choice of the appropriate wavelet function.

First application in spectroscopic ET (using coiflets wavelets)



Three-dimensional imaging of localized surface plasmon resonances of metal nanoparticles.
 Nicoletti *et al.* Nature 2013, 502, 80.



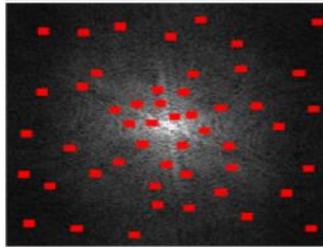
H. Cherkaoui et al. EUSIPCO 2018, 36.

PYSAP-ETOMO: AN OPEN-SOURCE TOOLBOX FOR COMPRESSED SENSING ELECTRON TOMOGRAPHY

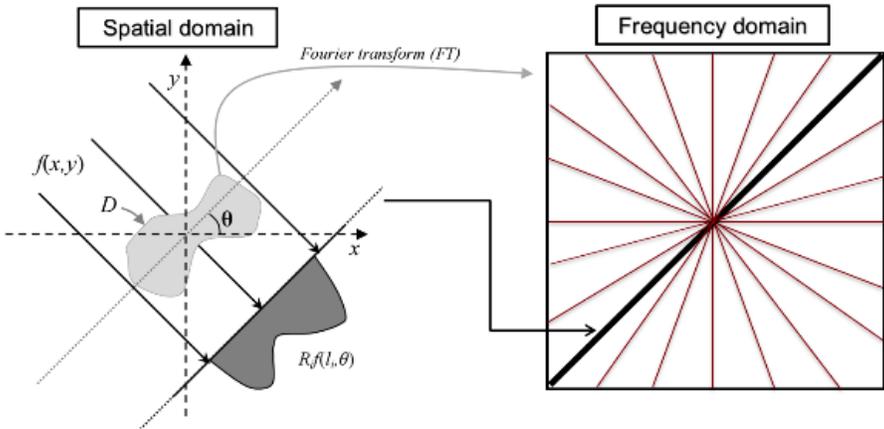
MRI



Frequency domain



ET



$$\underset{x}{\operatorname{argmin}} \left\{ \frac{1}{2} \|Px - y\|_2^2 + \lambda \|Rx\|_1 \right\}$$

Optimization algorithms	Projection operators	Sparsity transforms
Proximal gradient methods: <i>FISTA</i> <i>POGM</i>	Fourier-based: Non-uniform FFT	Gradient-based: TV HOTV TGV
Primal-dual methods: Condat-Vu	Radon-based: <i>Radon transform and the back-projection operator</i>	Wavelet-based: Pywavelets (e.g.: Haar, Bior4.4)
Options: Positivity constraint Soft thresholding and reweighting		<i>Sparse2D</i> (e.g.: <i>Ridgelets</i> , <i>Curvelets</i>)

Packages imported: Astra, PyNUFFT, Pywavelets and Modopt.

<https://github.com/CEA-COSMIC/pysap-etomo>

Collaboration with CEA-Neurospin (MRI)

M. Jacob et al., Ultramicroscopy 2021, 255, 113289.

OTHER OPEN-SOURCE PACKAGES FOR 3D RECONSTRUCTION

Name	General features	Reconstruction algorithms
Astra toolbox	Initially developed for X-ray tomography GPU-based implementations. Incorporated in Inspect3D (FEI)	Standard reconstruction algorithms + TV plugin
Tomopy	Initially developed for X-ray tomography CPU-based implementations. Recently integrated with Astra toolbox.	Standard reconstruction algorithms
Tomotools	Developed for electron tomography Tools for alignment + reconstruction.	Standard reconstruction algorithms (Astra + Tomopy)
Tomviz	Open source platform for alignment, reconstruction and visualization.	Standard reconstruction algorithms + TV
Matlab package (T. Sanders et al., Ultramicroscopy 2017, 174: 97)	Alignment, inpainting and denoising.	TV, HOTV, and multiscale HOTV.
Graptor (R. Huber et al., Nanoscale 2019, 11:5617)	Developed for EELS/EDS tomography GPU-based implementations.	TGV algorithm and multi-modal reconstruction approach
PySAP-etomo (M. Jacob et al., Ultramicroscopy 2021, 255: 113289)	<i>Adaptation of PySAP + Modop libraries Includes Astra and Pywavelet.</i>	<i>Implementation of gradient-based (TV, TGV, HOTV) and wavelet-based methods.</i>

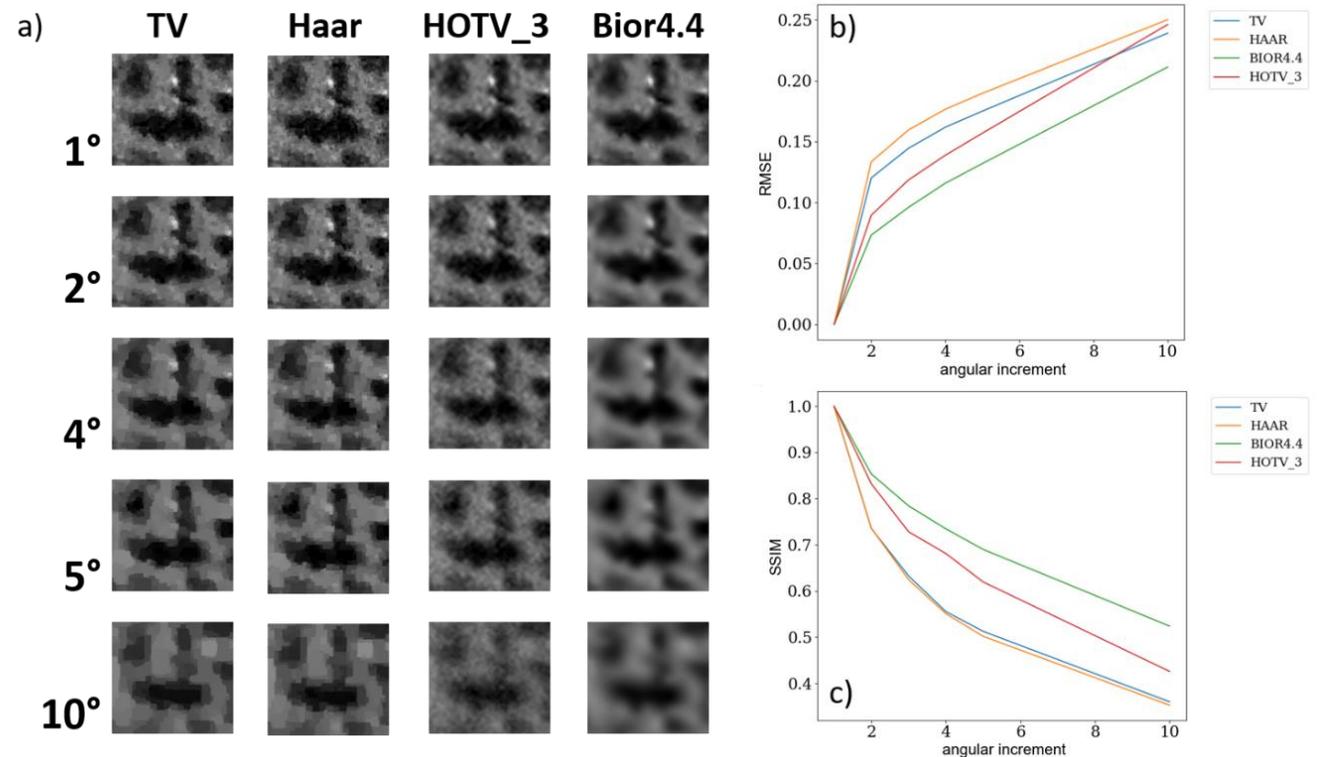
Dataset: Er-doped porous Si structure
HAADF-STEM mode
Tilt angles: $-90^\circ:1^\circ:+89^\circ$

TV/Haar: staircasing artifacts due to the piecewise constancy assumption.

HOTV_3 : no staircasing artifacts. Noise-like oscillations appear with large tilt increments.

Bior4.4: best results. Induces smoothness with large tilt increments

Effect of angular under-sampling

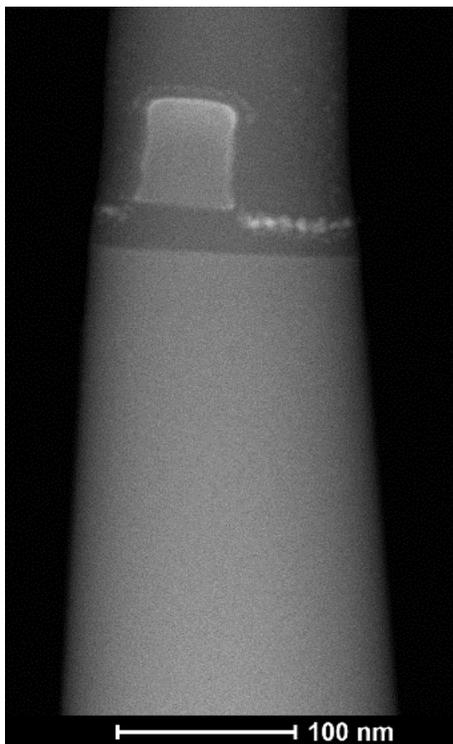


TV, Haar, HOTV_3 and Bior4.4 reconstructions with 1°, 2°, 4°, 5° and 10° increments. (b) RMSE and (c) SSIM scores showing the evolution of the image quality as function of the angular increment (in degrees).

HAADF-STEM AND EDX-STEM TOMOGRAPHY OF AS-DOPED SI FIN-SHAPED STRUCTURE

Aim of the study:

- Conformality of As implantation.
- Dopant depth profiling in 3D.
- Roughness of the sidewalls of the structure.



HAADF-STEM acquisition:

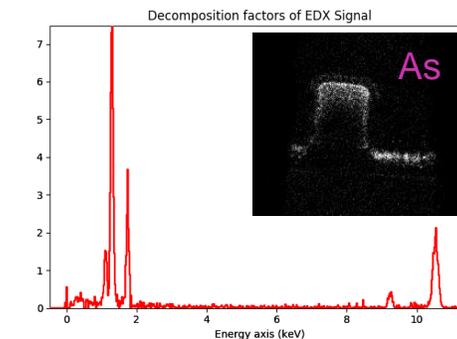
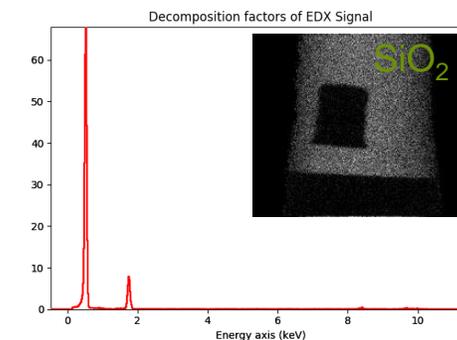
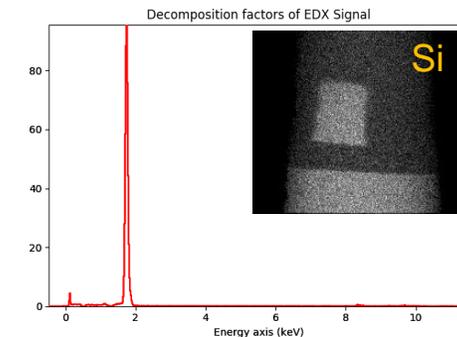
- Tilt series: $-90^{\circ}:5^{\circ}:+90^{\circ}$
- Frame size: 2048x2048 pixels
- Pixel size : 0.26nm
- 15sec frame time

EDS-STEM acquisition

- Tilt series: $-90^{\circ}:10^{\circ}:+90^{\circ}$
- Datacube size: 193x163x2048
- Pixel size : 1nm
- 10min frame time

Data processing

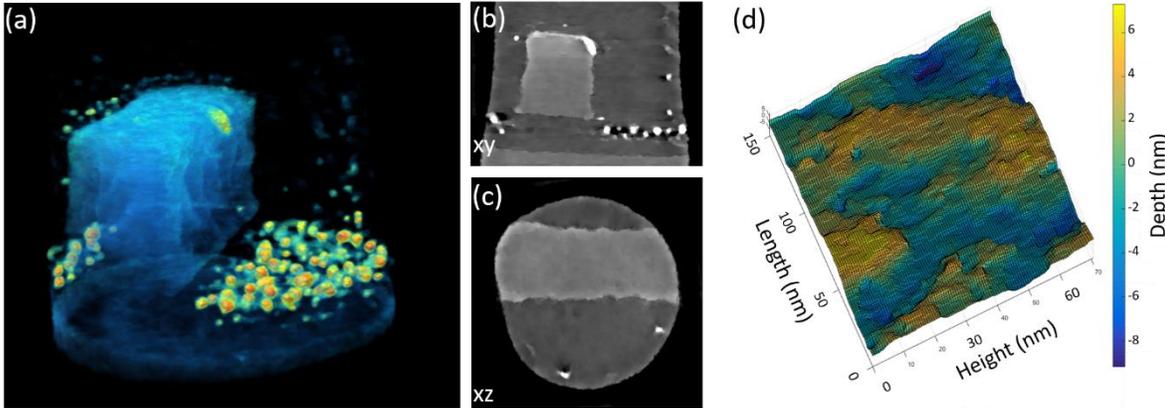
- NMF
- CS reconstruction using TV



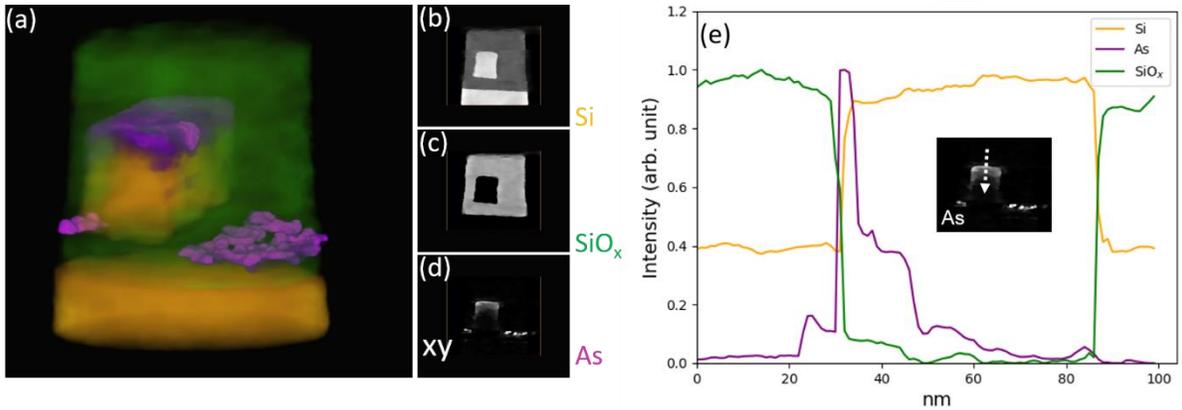
Chemical phase analysis by NMF

HAADF-STEM AND EDX-STEM TOMOGRAPHY OF AS-DOPED SI FIN-SHAPED STRUCTURE

HAADF-STEM tomography
3D information about sidewall roughness

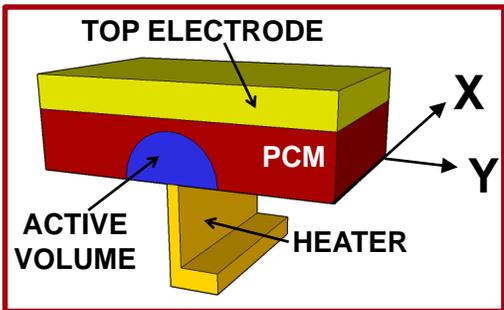


STEM-EDX tomography
3D information about As implantation

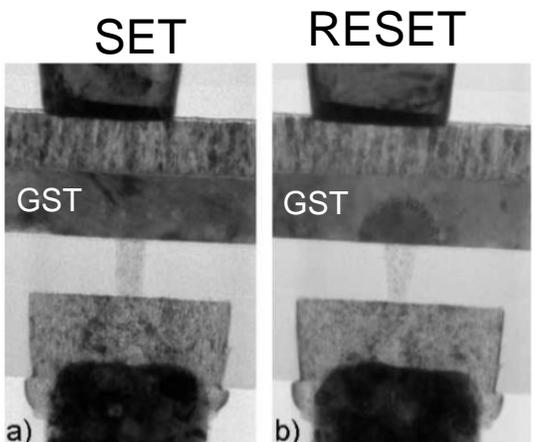


	STEM-EDX tomography	STEM-HAADF tomography
RMS roughness	-	~3 nm
Average precipitate volume	~20 nm ³	~15 nm ³
As implantation depth	~20 nm	-

STEM-EELS TOMOGRAPHY OF A GE-RICH GE-SB-TE (GST) THIN FILM FOR PHASE-CHANGE MEMORY (PCM) APPLICATIONS

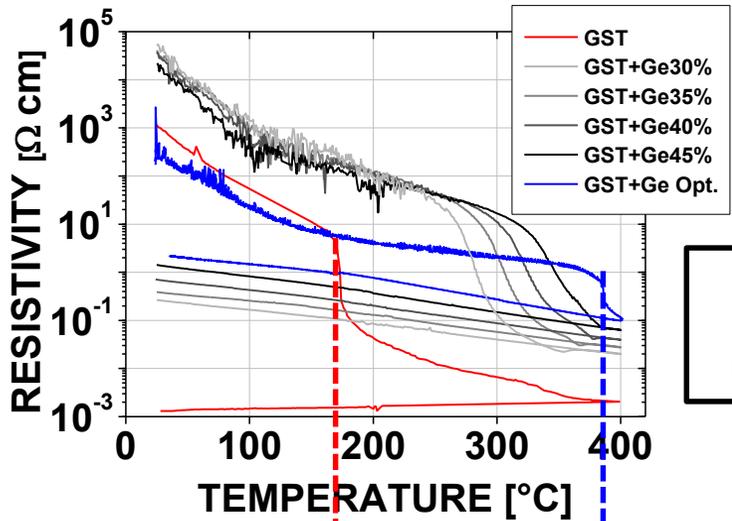


Example of an industrial PCM device



From: Phase change materials: science and applications, S. Raoux and M. Wuttig, Springer Verlag, New York, 2009.

Current challenge: PCM memory devices stability is challenged at high temperature (automotive applications).



Ge-rich GST crystallisation
↓
Phase separation GST & Ge

$Ge_2Sb_2Te_5$
 $T_c \sim 170^\circ C$

$Ge\text{-rich GST}$
 $T_c \sim 380^\circ C$

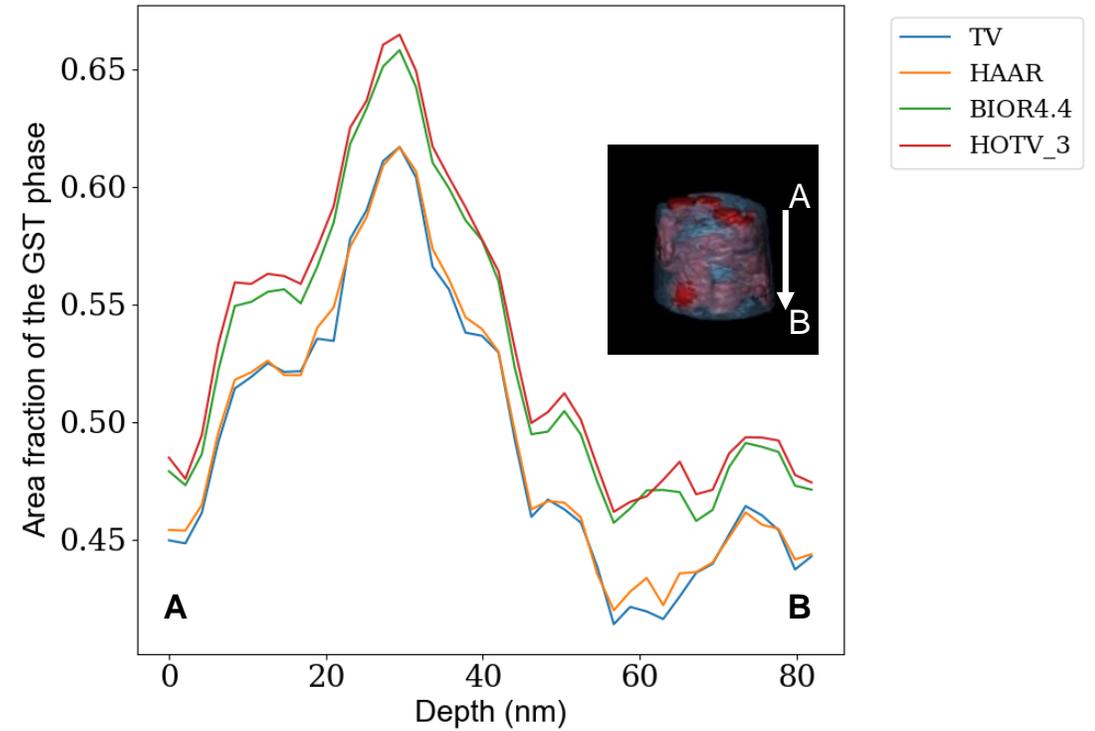
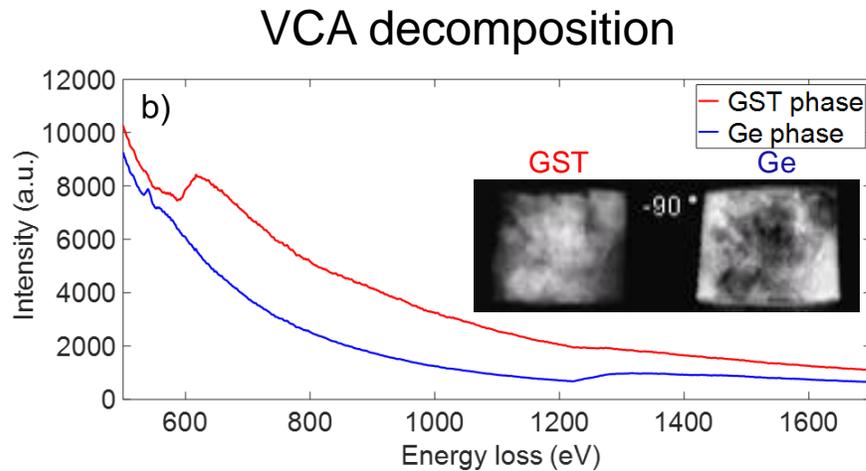
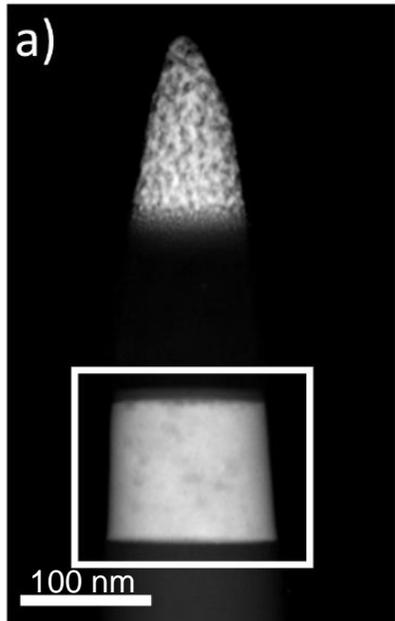
Increase of Ge at. %
↓
Increase of crystallization temperature (T_c)

STEM-EELS TOMOGRAPHY OF A GE-RICH GE-SB-TE (GST) THIN FILM FOR PHASE-CHANGE MEMORY (PCM) APPLICATIONS

HAADF-STEM (-90°:5°:+90°): 1024x1024 pixels, pixel size: 0.53nm, frame time: 16.7sec.

STEM-EELS (-90°:10°:+90°): 100x75 pixels, pixel size: 2.04nm, exposure time: 0.1sec (450eV, 1eV/ch), SI acquisition time: 18min.

Data processing: VCA + CS reconstruction using TV, Haar, HOTV_3 and undecimated biorthogonal wavelets (Bior4.4)



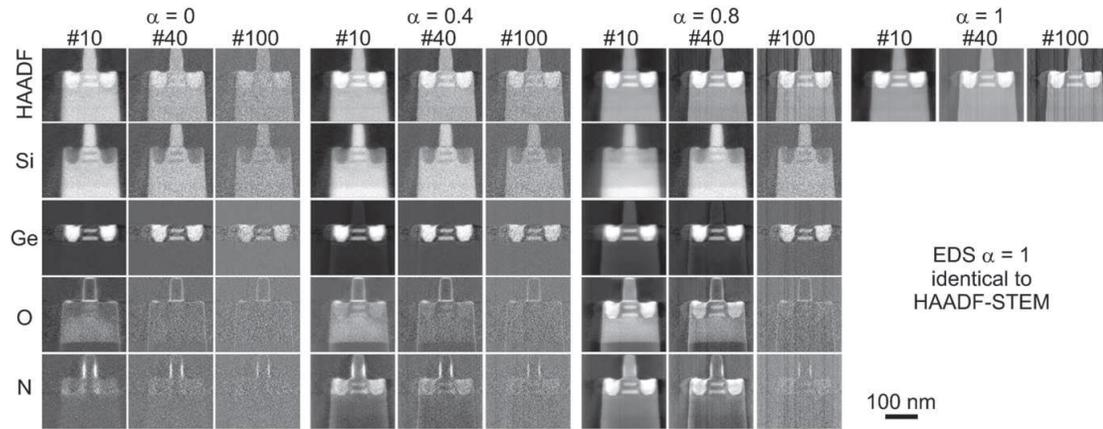
Volume fraction of the GST phase:

Bior4.4: 0.527	Haar: 0.494
HOTV_3: 0.533	TV: 0.491

A HYBRID APPROACH FOR IMPROVING THE QUALITY OF EDX-STEM RECONSTRUCTIONS

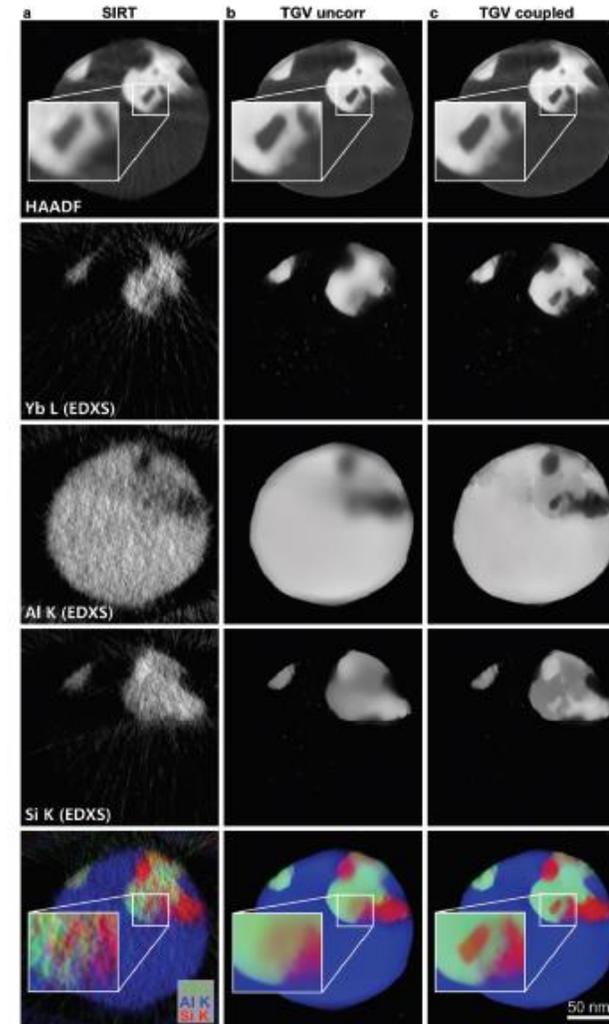
HEBT: HAADF-EDS bimodal tomographic reconstruction.
 Assumption: HAADF-STEM projection images are the linear sum of the EDX maps for all present elements.

TGV coupled: joint multi-channel reconstruction of HAADF and EDX data. Assumption: similar interface positions for all reconstructions.



HEBT approach

H. Bender et al., Semicond. Sci. Technol. 2019, 34, 114002.



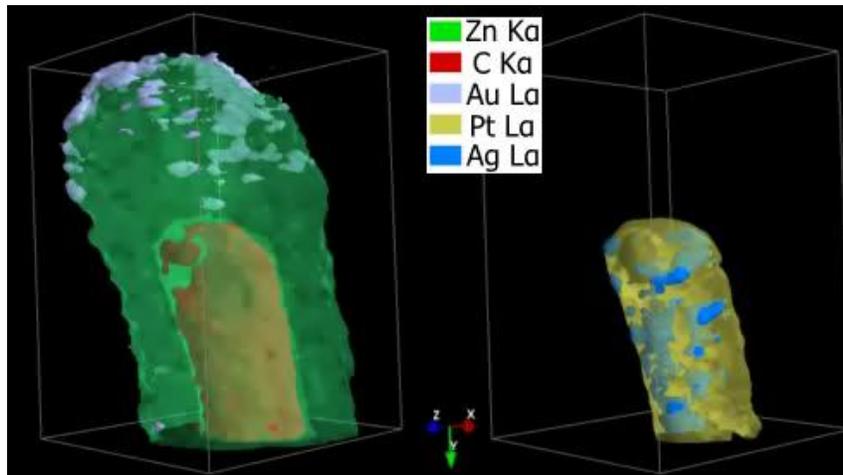
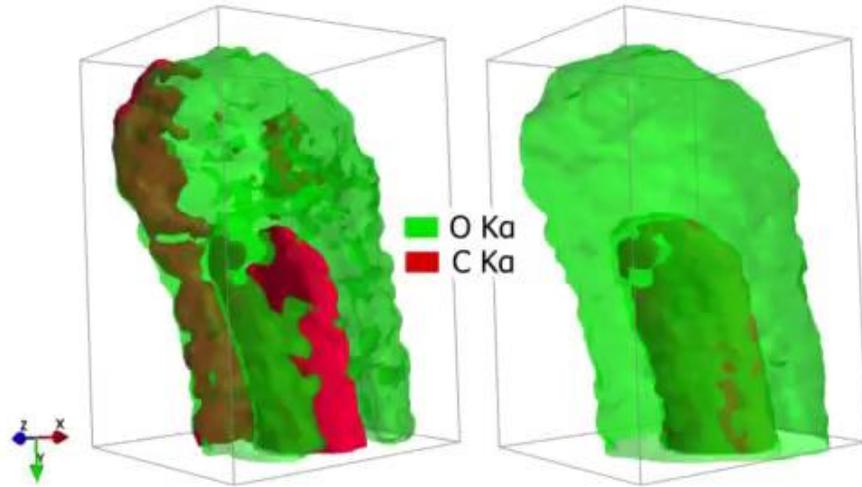
TGV coupled approach

R. Huber et al., Nanoscale 2019, 11, 5617.

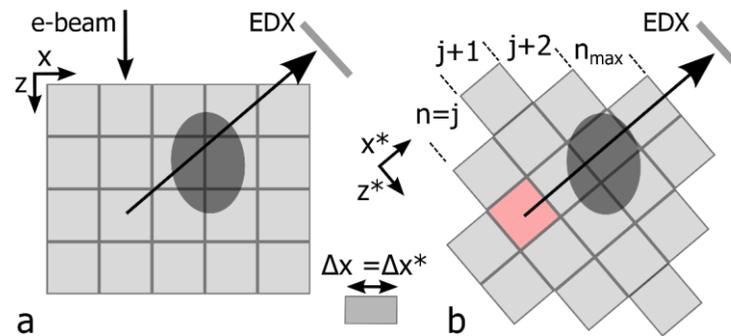
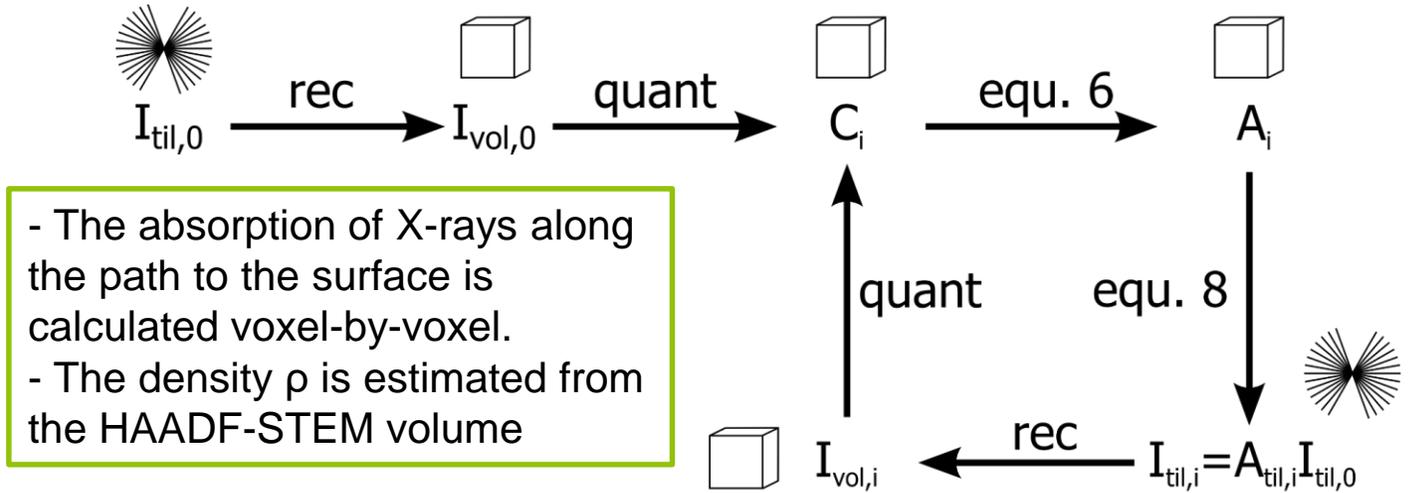
A HYBRID APPROACH FOR ABSORPTION CORRECTION IN STEM-EDX TOMOGRAPHY

uncorrected

corrected



Burdet et al., Ultramicrosc. 2016, 160: 118



$$\frac{I}{I_j} = \exp\left(-\sum_{n=j+1}^{n_{max}} \frac{\mu}{\rho} \rho_n \Delta x\right) \quad (6)$$

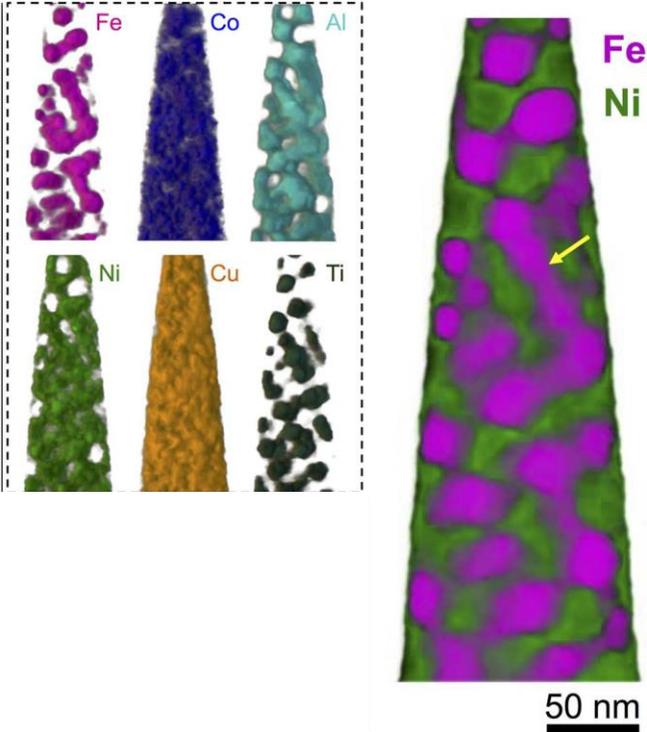
$$A_{til,i} = \frac{[I_{vol,i}]_{til}}{[I_{vol,0}]_{til}} = \frac{[I_{vol,0} A_i]_{til}}{[I_{vol,0}]_{til}} \quad (8)$$

Detector geometry

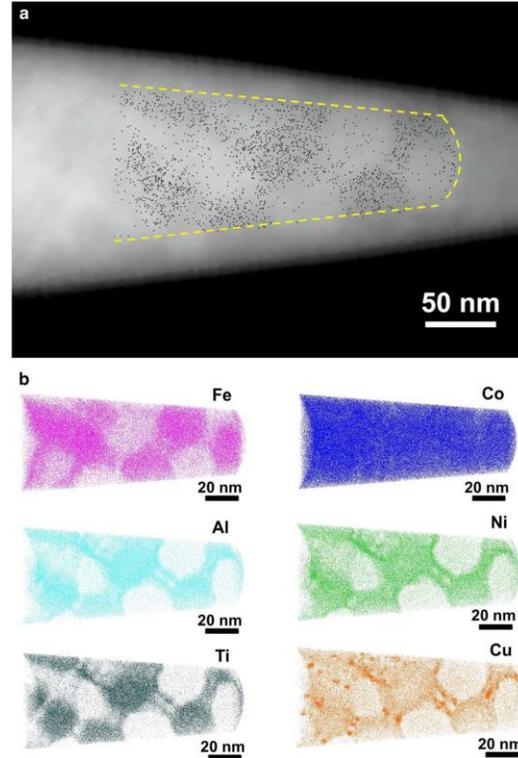
Slater et al., Ultramicroscopy 162 (2016) 61–73
 Xu et al., Ultramicroscopy 164 (2016) 51–61

FUTURE PROSPECTS: CORRELATIVE SPECTROSCOPIC ET/APT

EDX-STEM tomography



APT



EELS/EDX-STEM tomography:

Non-destructive, large fields of view, high spatial fidelity, limited spatial resolution (few nms), LLD $\sim 1 \times 10^{20}$ at.cm⁻³, quantification methods not fully developed.

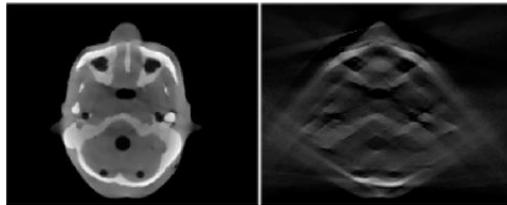
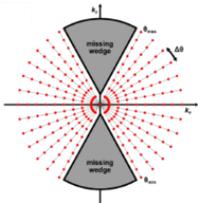
APT:

Destructive, small fields of view, limited spatial fidelity, high spatial resolution, LLD $\sim 5 \times 10^{18}$ at.cm⁻³, quantitative method.

Phase Separation in an Alnico 8 Alloy.
Guo et al., Microsc. Microanal. 2016, 22, 1251.

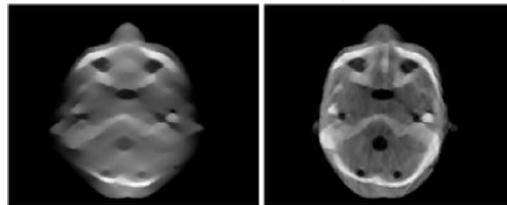
FUTURE PROSPECTS: DEEP LEARNING APPROACHES FOR LOW-DOSE AND LIMITED-ANGLE TOMOGRAPHY

Limited-angle tomography



Reference

Standard algorithm (FBP)

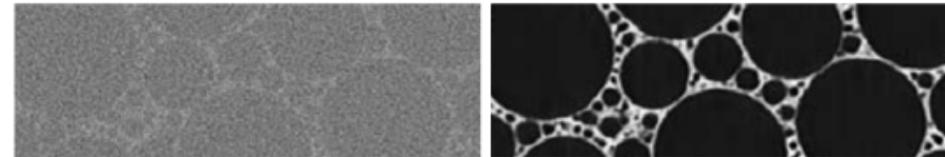


CS approach (TV)

DL approach (GAN)

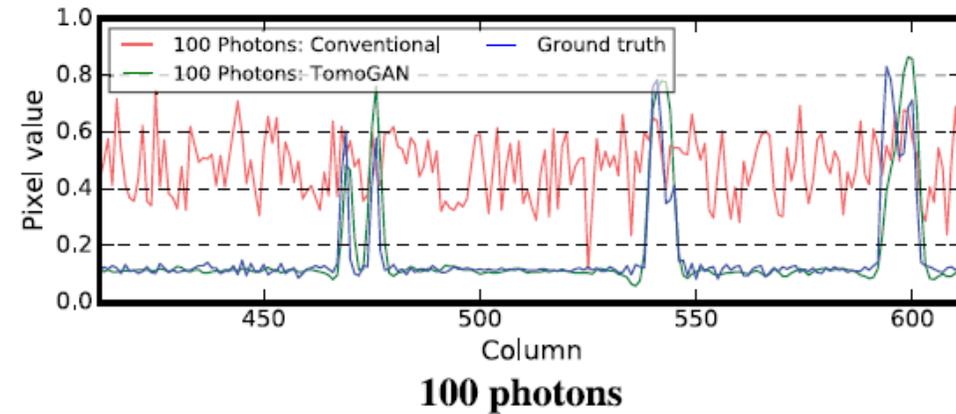
Z. Li et al., Sensors 2019, 19, 3941.

Low-dose tomography



Conventional.

TomoGAN.

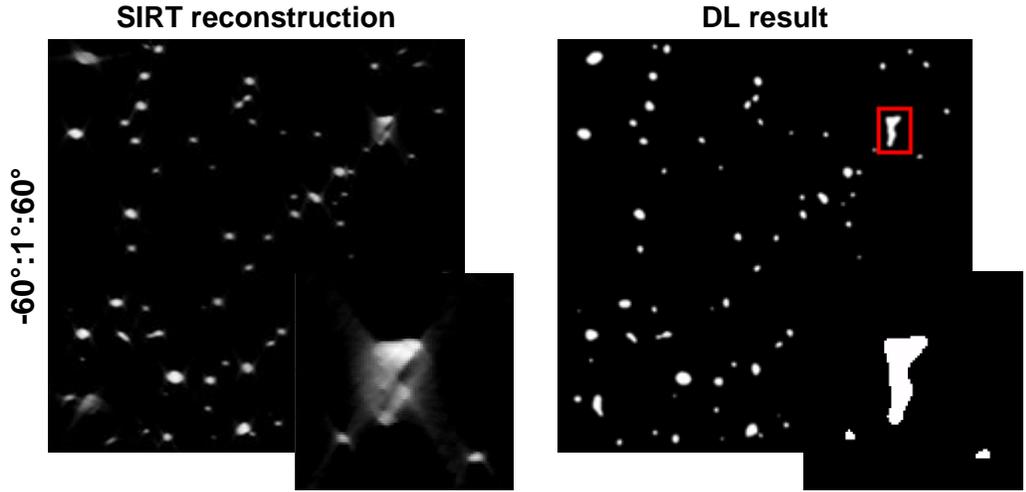
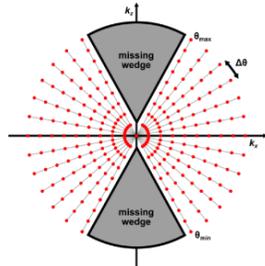
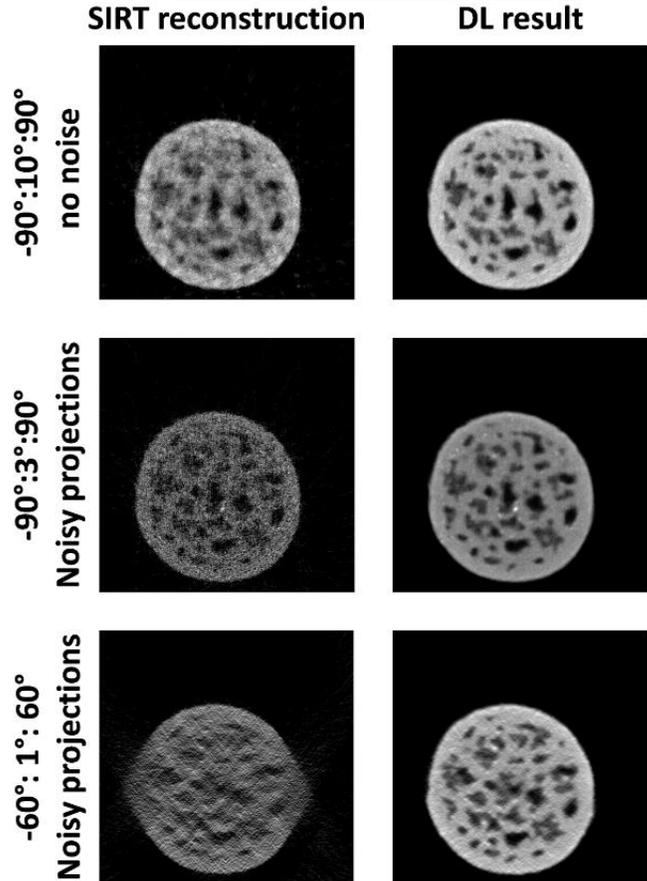
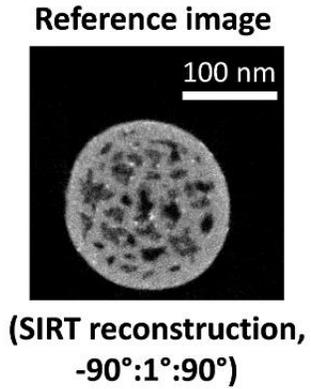


Z. Liu et al., J. Opt. Soc. Am. A 2020, 37, 422.

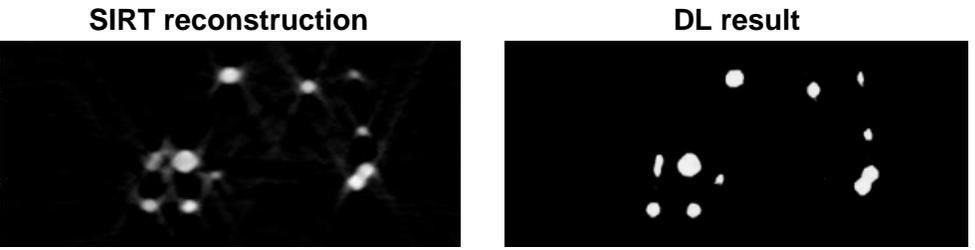
DEEP LEARNING APPROACHES FOR ELECTRON TOMOGRAPHY

Porous structures

Nanoparticles



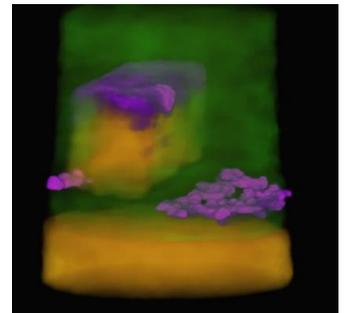
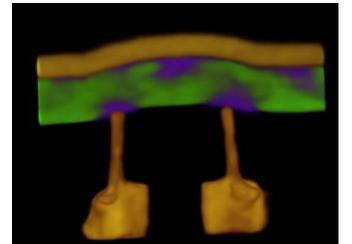
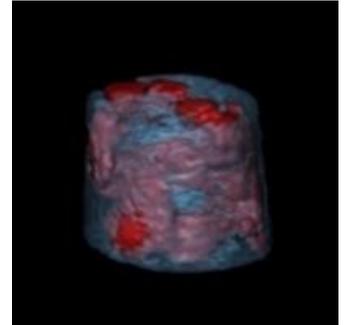
HAADF-STEM tomography of Pt catalysts (-59°:2°:63°)



Correction of missing wedge artefacts

Tilt range	Number of projections	Poisson noise added	SIRT reconstruction PSNR / SSIM	DL output PSNR / SSIM
180°	18	no	22.5 / 0.782	25.8 / 0.807
180°	60	yes	19.8 / 0.675	26.1 / 0.806
120°	120	yes	19.6 / 0.633	25.8 / 0.823

- Analytical ET is very promising for comprehensive semiconductor device analysis with 3D information about morphology *and* chemistry.
- Simultaneous EDX and precession electron diffraction was demonstrated in 2D and can be extend to 3D for more complete information (morphology + chemistry + *structure*).
- The technique will certainly evolve in the future, with continuous progress in:
 - Instrumentation (direct electron detectors, EDX systems with solid angles reaching 4 sr, EELS spectrometers with 8000 spectra/s, etc)
 - Data processing (machine learning tools for spectral analysis, reconstruction algorithms based on CS and DL)
- The correlation of analytical ET with APT is a promising route that can benefit both techniques.
- DL approaches are beginning to revolutionize ET (high-speed, low-dose, correction of missing wedge artifacts).



CEA DRT/Leti/DPFT:

M. Jacob
M-L. Grouzelle
G. Biagi
A. Grenier
P. Quéméré

ST Crolles:

F. Lorut
A. Valery

CEA DRF/IRFU:

J-L. Starck
S. Farrens

CEA DRT/Leti/DCOS:

G. Navarro

CEA DRF/NEUROSPIN:

P. Ciuciu

Thank you for your attention!

Email: zineb.saghi@cea.fr

